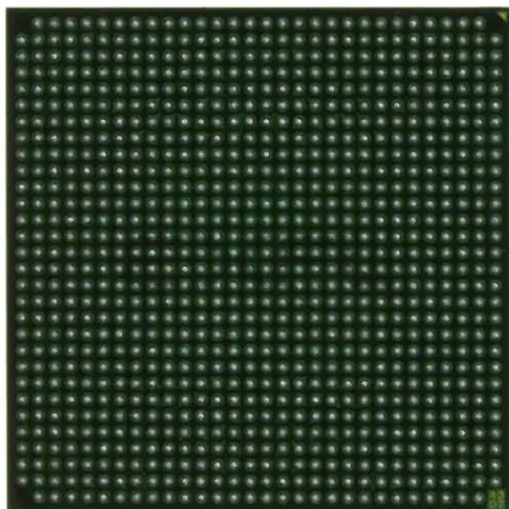




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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2320
Number of Logic Elements/Cells	20880
Total RAM Bits	1622016
Number of I/O	556
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FCBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp20-5ffg896c

Table 9: Supported Differential Signal I/O Standards

I/O Standard	Output V _{CCO}	Input V _{CCO}	Input V _{REF}	Output V _{OD}
LDT_25	2.5	N/R	N/R	0.500 – 0.740
LVDS_25	2.5	N/R	N/R	0.247 – 0.454
LVDSEXT_25	2.5	N/R	N/R	0.440 – 0.820
BLVDS_25	2.5	N/R	N/R	0.250 – 0.450
ULVDS_25	2.5	N/R	N/R	0.500 – 0.740
LVPECL_25	2.5	N/R	N/R	0.345 – 1.185
LDT_25_DT ⁽¹⁾	2.5	2.5	N/R	0.500 – 0.740
LVDS_25_DT ⁽¹⁾	2.5	2.5	N/R	0.247 – 0.454
LVDSEXT_25_DT ⁽¹⁾	2.5	2.5	N/R	0.330 – 0.700
ULVDS_25_DT ⁽¹⁾	2.5	2.5	N/R	0.500 – 0.740

Notes:

1. These standards support on-chip 100Ω termination.
2. N/R = no requirement.

Table 10: Supported DCI I/O Standards

I/O Standard	Output V _{CCO}	Input V _{CCO}	Input V _{REF}	Termination Type
LVDCI_33 ⁽¹⁾	3.3	3.3	N/R	Series
LVDCI_25	2.5	2.5	N/R	Series
LVDCI_DV2_25	2.5	2.5	N/R	Series
LVDCI_18	1.8	1.8	N/R	Series
LVDCI_DV2_18	1.8	1.8	N/R	Series
LVDCI_15	1.5	1.5	N/R	Series
LVDCI_DV2_15	1.5	1.5	N/R	Series
GTL_DCI	1.2	1.2	0.8	Single
GTLP_DCI	1.5	1.5	1.0	Single
HSTL_I_DCI	1.5	1.5	0.75	Split
HSTL_II_DCI	1.5	1.5	0.75	Split
HSTL_III_DCI	1.5	1.5	0.9	Single
HSTL_IV_DCI	1.5	1.5	0.9	Single
HSTL_I_DCI_18	1.8	1.8	0.9	Split
HSTL_II_DCI_18	1.8	1.8	0.9	Split
HSTL_III_DCI_18	1.8	1.8	1.1	Single
HSTL_IV_DCI_18	1.8	1.8	1.1	Single
SSTL2_I_DCI ⁽²⁾	2.5	2.5	1.25	Split
SSTL2_II_DCI ⁽²⁾	2.5	2.5	1.25	Split
SSTL18_I_DCI ⁽³⁾	1.8	1.8	0.9	Split
SSTL18_II_DCI	1.8	1.8	0.9	Split

Table 10: Supported DCI I/O Standards (Continued)

I/O Standard	Output V _{CCO}	Input V _{CCO}	Input V _{REF}	Termination Type
LVDS_25_DCI	2.5	2.5	N/R	Split
LVDSEXT_25_DCI	2.5	2.5	N/R	Split

Notes:

1. LVDCI_XX is LVCMOS output controlled impedance buffers, matching all or half of the reference resistors.
2. These are SSTL compatible.
3. SSTL18_I is not a JEDEC-supported standard.
4. N/R = no requirement.

Logic Resources

IOB blocks include six storage elements, as shown in Figure 19.

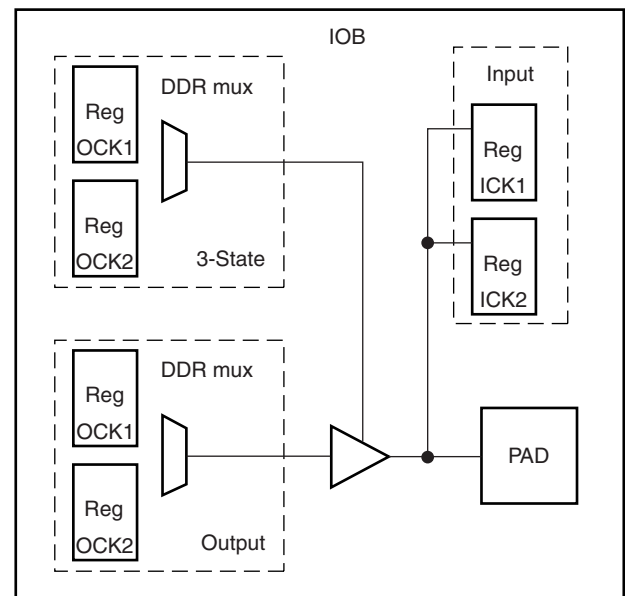


Figure 19: Virtex-II Pro IOB Block

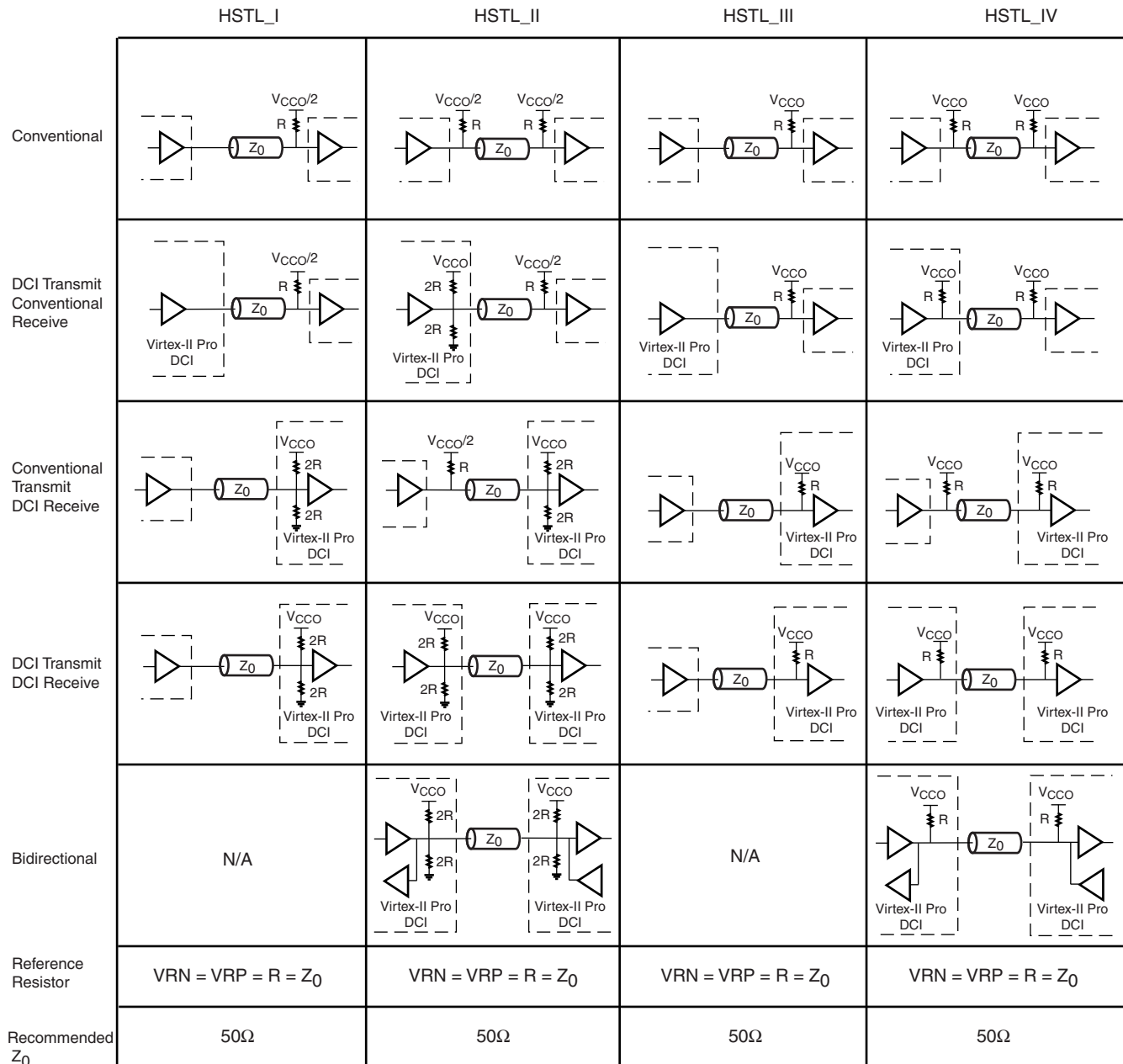
Each storage element can be configured either as an edge-triggered D-type flip-flop or as a level-sensitive latch. On the input, output, and 3-state path, one or two DDR registers can be used.

Double data rate is directly accomplished by the two registers on each path, clocked by the rising edges (or falling edges) from two different clock nets. The two clock signals are generated by the DCM and must be 180 degrees out of phase, as shown in Figure 20. There are two input, output, and 3-state data signals, each being alternately clocked out.

Table 15: SelectIO-Ultra Differential Buffers With On-Chip Termination

I/O Standard Description	IOSTANDARD Attribute	
	External Termination	On-Chip Termination
LVDS 2.5V	LVDS_25	LVDS_25_DCI
LVDS Extended 2.5V	LVDSEXT_25	LVDSEXT_25_DCI

Figure 28 provides examples illustrating the use of the HSTL_I_DCI, HSTL_II_DCI, HSTL_III_DCI, and HSTL_IV_DCI I/O standards. For a complete list, see the [Virtex-II Pro Platform FPGA User Guide](#).



DS083-2_65a_082102

Figure 28: HSTL DCI Usage Examples

Sum of Products

Each Virtex-II Pro slice has a dedicated OR gate named ORCY, ORing together outputs from the slices carryout and the ORCY from an adjacent slice. The ORCY gate with the dedicated Sum of Products (SOP) chain are designed for

implementing large, flexible SOP chains. One input of each ORCY is connected through the fast SOP chain to the output of the previous ORCY in the same slice row. The second input is connected to the output of the top MUXCY in the same slice, as shown in Figure 43.

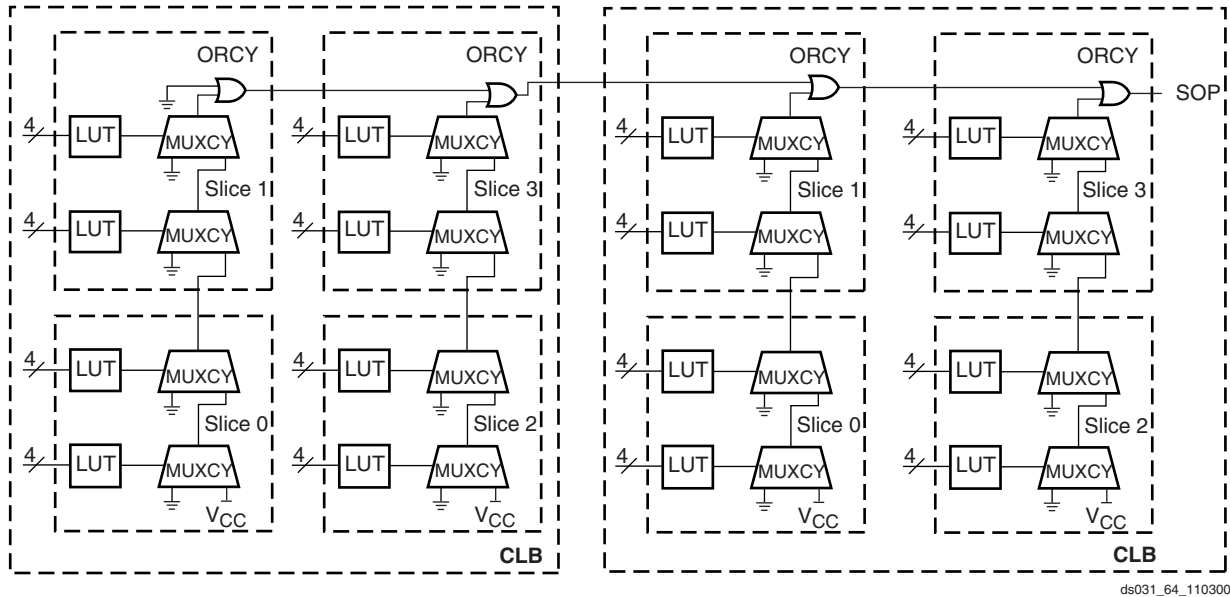


Figure 43: Horizontal Cascade Chain

LUTs and MUXCYs can implement large AND gates or other combinatorial logic functions. Figure 44 illustrates

LUT and MUXCY resources configured as a 16-input AND gate.

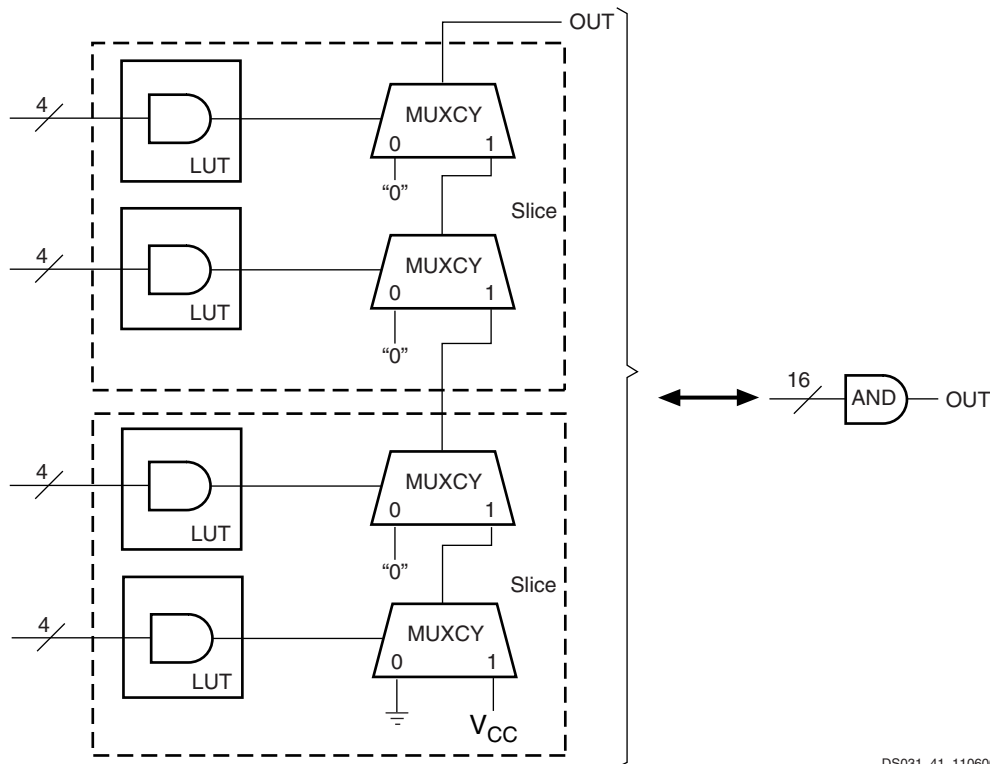


Figure 44: Wide-Input AND Gate (16 Inputs)

Routing

DCM and MGT Locations/Organization

Virtex-II Pro DCMs and serial transceivers (MGTs) are placed on the top and bottom of each block RAM and multiplier column in some combination, as shown in Table 31. The number of DCMs and RocketIO transceivers total twice the number of block RAM columns in the device. Refer to Figure 52, page 47 for an illustration of this in the XC2VP4 device.

Table 31: DCM and MGT Organization

Device	Block RAM Columns	DCMs	MGTs
XC2VP2	4	4	4
XC2VP4	4	4	4
XC2VP7	6	4	8
XC2VP20	8	8	8
XC2VPX20	8	8	8
XC2VP30	8	8	8
XC2VP40	10	8	12
XC2VP50	12	8	16
XC2VP70	14	8	20
XC2VPX70	14	8	20
XC2VP100	16	12	20

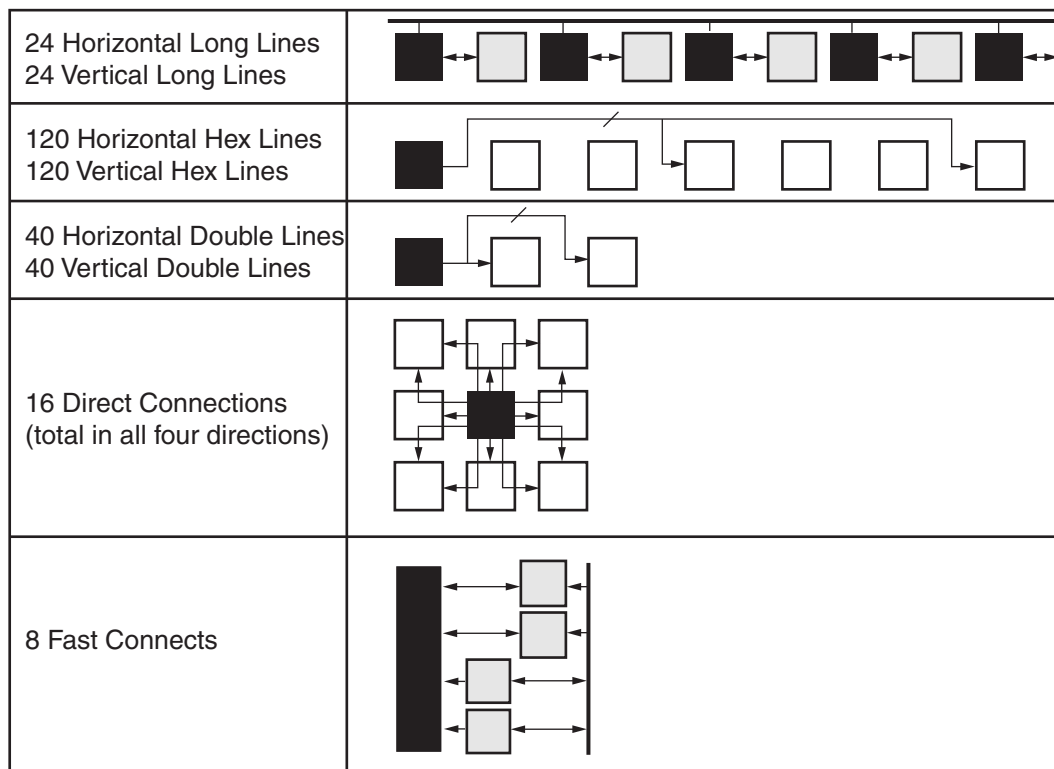
Place-and-route software takes advantage of this regular array to deliver optimum system performance and fast compile times. The segmented routing resources are essential to guarantee IP cores portability and to efficiently handle an incremental design flow that is based on modular implementations. Total design time is reduced due to fewer and shorter design iterations.

Hierarchical Routing Resources

Most Virtex-II Pro signals are routed using the global routing resources, which are located in horizontal and vertical routing channels between each switch matrix.

As shown in Figure 64, page 54, Virtex-II Pro has fully buffered programmable interconnections, with a number of resources counted between any two adjacent switch matrix rows or columns. Fanout has minimal impact on the performance of each net.

- The long lines are bidirectional wires that distribute signals across the device. Vertical and horizontal long lines span the full height and width of the device.
- The hex lines route signals to every third or sixth block away in all four directions. Organized in a staggered pattern, hex lines can only be driven from one end. Hex-line signals can be accessed either at the endpoints or at the midpoint (three blocks from the source).



DS031_60_110200

Figure 64: Hierarchical Routing Resources

SelectIO-Ultra DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for I_{OL} and I_{OH} are guaranteed over the recommended operating conditions at the V_{OL} and V_{OH} test points. Only selected standards are tested. These are cho-

sen to ensure that all standards meet their specifications. The selected standards are tested at minimum V_{CCO} with the respective V_{OL} and V_{OH} voltage levels shown. Other standards are sample tested.

Table 6: DC Input and Output Levels

IOSTANDARD Attribute	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, min	V, max	V, min	V, max	V, max	V, min	mA	mA
LVTTL	-0.2	0.8	2.0	3.45	0.4	2.4	24	-24
LVC MOS33	-0.2	0.8	2.0	3.45	0.4	$V_{CCO} - 0.4$	24	-24
LVC MOS25	-0.2	0.7	1.7	$V_{CCO} + 0.4$	0.4	$V_{CCO} - 0.4$	24	-24
LVC MOS18	-0.2	30% V_{CCO}	70% V_{CCO}	$V_{CCO} + 0.4$	0.4	$V_{CCO} - 0.45$	16	-16
LVC MOS15	-0.2	30% V_{CCO}	70% V_{CCO}	$V_{CCO} + 0.4$	0.4	$V_{CCO} - 0.45$	16	-16
PCI33_3	-0.2	30% V_{CCO}	50% V_{CCO}	3.6	10% V_{CCO}	90% V_{CCO}		
PCI66_3	-0.2	30% V_{CCO}	50% V_{CCO}	3.6	10% V_{CCO}	90% V_{CCO}		
PCIX	-0.2	Note (1)	Note (1)	Note (1)	Note (1)	Note (1)	Note (1)	Note (1)
GTLP	-0.2	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.4$	0.6	n/a	36	n/a
GTL	-0.2	$V_{REF} - 0.05$	$V_{REF} + 0.05$	$V_{CCO} + 0.4$	0.4	n/a	40	n/a
HSTL_I	-0.2	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.4$	0.4 ⁽²⁾	$V_{CCO} - 0.4$	8 ⁽²⁾	-8 ⁽²⁾
HSTL_II	-0.2	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.4$	0.4 ⁽²⁾	$V_{CCO} - 0.4$	16 ⁽²⁾	-16 ⁽²⁾
HSTL_III	-0.2	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.4$	0.4 ⁽²⁾	$V_{CCO} - 0.4$	24 ⁽²⁾	-8 ⁽²⁾
HSTL_IV	-0.2	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.4$	0.4 ⁽²⁾	$V_{CCO} - 0.4$	48 ⁽²⁾	-8 ⁽²⁾
SSTL2_I	-0.2	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCO} + 0.3$	$V_{TT} - 0.61$	$V_{TT} + 0.61$	8.1	-8.1
SSTL2_II	-0.2	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCO} + 0.3$	$V_{TT} - 0.81$	$V_{TT} + 0.81$	16.2	-16.2
SSTL18_I	-0.2	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCO} + 0.3$	$V_{TT} - 0.61$	$V_{TT} + 0.61$	6.7	-6.7
SSTL18_II	-0.2	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCO} + 0.3$	$V_{TT} - 0.61$	$V_{TT} + 0.61$	13.4	-13.4

Notes:

1. Tested according to relevant specifications.
2. This applies to 1.5V and 1.8V HSTL.

LDT DC Specifications (LDT_25)

Table 7: LDT DC Specifications

DC Parameter	Symbol	Conditions	Min	Typ	Max	Units
Supply Voltage	V_{CCO}		2.38	2.5	2.63	V
Differential Output Voltage	V_{OD}	$R_T = 100$ ohm across Q and $\bar{Q}$ signals	495	600	715	mV
Change in V_{OD} Magnitude	ΔV_{OD}		-15		15	mV
Output Common Mode Voltage	V_{OCM}	$R_T = 100$ ohm across Q and $\bar{Q}$ signals	495	600	715	mV
Change in V_{OS} Magnitude	ΔV_{OCM}		-15		15	mV
Input Differential Voltage	V_{ID}		200	600	1000	mV
Change in V_{ID} Magnitude	ΔV_{ID}		-15		15	mV
Input Common Mode Voltage	V_{ICM}		440	600	780	mV
Change in V_{ICM} Magnitude	ΔV_{ICM}		-15		15	mV

Table 36: IOB Input Switching Characteristics Standard Adjustments (Continued)

Description	IOSTANDARD Attribute	Timing Parameter	Speed Grade			Units
			-7	-6	-5	
HSLVDCI, 1.8V	HSLVDCI_18	T _{IHSLVDCI_18}	0.59	0.68	0.75	ns
HSLVDCI, 2.5V	HSLVDCI_25	T _{IHSLVDCI_25}	0.59	0.68	0.75	ns
HSLVDCI, 3.3V	HSLVDCI_33	T _{IHSLVDCI_33}	0.59	0.68	0.75	ns
GTL (Gunning Transceiver Logic) with DCI	GTL_DCI	T _{IGTL_DCI}	0.49	0.57	0.62	ns
GTL Plus with DCI	GTLP_DCI	T _{IGTLP_DCI}	0.27	0.31	0.35	ns
HSTL (High-Speed Transceiver Logic), Class I, with DCI	HSTL_I_DCI	T _{IHSTL_I_DCI}	0.27	0.31	0.35	ns
HSTL, Class II, with DCI	HSTL_II_DCI	T _{IHSTL_II_DCI}	0.27	0.31	0.35	ns
HSTL, Class III, with DCI	HSTL_III_DCI	T _{IHSTL_III_DCI}	0.27	0.31	0.35	ns
HSTL, Class IV, with DCI	HSTL_IV_DCI	T _{IHSTL_IV_DCI}	0.27	0.31	0.35	ns
HSTL, Class I, 1.8V, with DCI	HSTL_I_DCI_18	T _{IHSTL_I_DCI_18}	0.27	0.31	0.35	ns
HSTL, Class II, 1.8V, with DCI	HSTL_II_DCI_18	T _{IHSTL_II_DCI_18}	0.27	0.31	0.35	ns
HSTL, Class III, 1.8V, with DCI	HSTL_III_DCI_18	T _{IHSTL_III_DCI_18}	0.27	0.31	0.35	ns
HSTL, Class IV, 1.8V, with DCI	HSTL_IV_DCI_18	T _{IHSTL_IV_DCI_18}	0.27	0.31	0.35	ns
SSTL (Stub Series Terminated Logic), Class I, 1.8V, with DCI	SSTL18_I_DCI	T _{ISSTL18_I_DCI}	0.62	0.72	0.79	ns
SSTL, Class II, 1.8V, with DCI	SSTL18_II_DCI	T _{ISSTL18_II_DCI}	0.64	0.73	0.81	ns
SSTL, Class I, 2.5V, with DCI	SSTL2_I_DCI	T _{ISSTL2_I_DCI}	0.17	0.20	0.22	ns
SSTL, Class II, 2.5V, with DCI	SSTL2_II_DCI	T _{ISSTL2_II_DCI}	0.17	0.20	0.22	ns
LVDS, 2.5V, with DCI	LVDS_25_DCI	T _{ILVDS_25_DCI}	0.31	0.36	0.40	ns
LVDSEXT, 2.5V, with DCI	LVDSEXT_25_DCI	T _{ILVDSEXT_25_DCI}	0.33	0.37	0.41	ns
LVDS, 2.5V, with Differential Termination (DT)	LVDS_25_DT	T _{ILVDS_25_DT}	0.31	0.36	0.40	ns
LVDSEXT, 2.5V, with DT	LVDSEXT_25_DT	T _{ILVDSEXT_25_DT}	0.33	0.37	0.41	ns
ULVDS, 2.5V, with DT	ULVDS_25_DT	T _{IULVDS_25_DT}	0.31	0.36	0.40	ns
LDT, 2.5V, with DT	LDT_25_DT	T _{ILD_25_DT}	0.31	0.36	0.40	ns

Date	Version	Revision
12/05/03 (cont'd)	3.0 (cont'd)	- Non-speedsfile parameter values added or updated: Table 3: I_{BATT}. Table 4: For XC2VP100, I_{CCINTQ}, I_{CCOQ}, and I_{CCAUXQ}. Table 5: For XC2VP100, $I_{CCINTMIN}$. Table 17: T_{CPWL} and T_{CPWH}. Table 25: Added explanatory footnote to T_{RXLAT} (MGT receiver latency) max value. Table 57: Added Footnote (3) regarding use of CLKIN_DIVIDE_BY_2 attribute.
02/19/04	3.1	- Updated time and frequency parameters as per speedsfile v1.85. Table 2, Recommended Operating Conditions: Revised Footnotes (4) and (6). Table 4, Quiescent Supply Current: Added Footnote (1) and updated Typical parameters. Table 10, LVPECL DC Specifications: Added parameter values for Maximum Differential Input Voltage (LVPECL). Table 14, Register-to-Register Performance: Removed reference to a number of designs for which test data is no longer provided. Table 16, Processor Clocks Absolute AC Characteristics: Added Footnote (1) referring to XAPP755. - Added Table 41, Clock Distribution Switching Characteristics. - Revised section Configuration Timing, page 39 through page 41, and JTAG Test Access Port Switching Characteristics, page 42, with improved timing diagrams, parameter tables, and organization. Table 50, Master/Slave Serial Mode Timing Characteristics, and Table 51, SelectMAP Mode Write Timing Characteristics: Added parameter $F_{CC_STARTUP}$. Table 51, SelectMAP Mode Write Timing Characteristics: Broke out T_{SMDC}/T_{SMCCD}, DATA[0:7] setup/hold time, by device, and added new parameter specifications for XC2VP70 and XC2VP100 devices. Table 57, Operating Frequency Ranges: Added callouts for existing Footnote (3) to the four CLKIN parameters. Added new Footnote (4) to the four CLKIN parameters. Added new Footnote (5) to CLK2X, CLK2X180. Added new Footnote (6) to CLK2X, CLK2X180; CLK0, CLK180; and CLKIN (using DLL outputs).
03/09/04	3.1.1	Recompiled for backward compatibility with Acrobat 4 and above. No content changes.
04/22/04	3.2	Table 2, Recommended Operating Conditions: Corrected VTTX/VTRX lower voltage limit from 1.8V to 1.6V. Table 5, Power-On Current for Virtex-II Pro Devices: Added Footnote (2) stating that listed I_{CCOMIN} values apply to the entire device (all banks). Table 40, Output Delay Measurement Methodology: Corrected V_{MEAS} for LVTTTL from 1.4V to 1.65V. Table 57, Operating Frequency Ranges: Corrected CLKOUT_FREQ_1X_LF_MAX and CLKIN_FREQ_DLL_LF_MAX for -7 devices from 210 MHz to 270 MHz. Table 65, Package Skew: Removed XC2VP40FF1517.
06/30/04	4.0	Merged in DS110-3 (Module 3 of Virtex-II Pro X data sheet). This merge added numerous previously unpublished RocketIO X MGT parameters. Specifications in this revision are from speedsfile v1.86 .

Virtex-II Pro Pin Definitions

This section describes the pinouts for Virtex-II Pro devices in the following packages:

- FG256/FGG256, FG456/FGG456, and FG676/FGG676: wire-bond fine-pitch BGA of 1.00 mm pitch
- FF672, FF896, FF1148, FF1152, FF1517, FF1696, and FF1704: flip-chip fine-pitch BGA of 1.00 mm pitch

All of the devices supported in a particular package are pin-out-compatible and are listed in the same table (one table

per package). Pins that are not available for smaller devices are listed in right-hand columns.

Each device is split into eight I/O banks to allow for flexibility in the choice of I/O standards. Global pins, including JTAG, configuration, and power/ground pins, are listed at the end of each table. **Table 4** provides definitions for all pin types.

All Virtex-II Pro pinout tables are available on the distribution CD-ROM, or on the web (at <http://www.xilinx.com>).

Pin Definitions

Table 4 provides a description of each pin type listed in Virtex-II Pro pinout tables.

Table 4: Virtex-II Pro Pin Definitions

Pin Name	Direction	Description
User I/O Pins:		
IO_LXXY_#	Input/Output/ Bidirectional	All user I/O pins are capable of differential signalling and can implement LVDS, ULVDS, BLVDS, LVPECL, or LDT pairs. Each user I/O is labeled "IO_LXXY_#", where: IO indicates a user I/O pin. LXXY indicates a differential pair, with XX a unique pair in the bank and Y = P/N for the positive and negative sides of the differential pair. # indicates the bank number (0 through 7)
Dual-Function Pins:		
IO_LXXY_#/ZZZ		The <i>dual-function pins</i> are labelled "IO_LXXY_#/ZZZ", where "ZZZ" can be one of the following pins: Per Bank - VRP , VRN , or VREF Globally - GCLKX(S/P) , BUSY/DOUT , INIT_B , D0/DIN – D7 , RDWR_B , or CS_B These dual functions are defined in the following section:
"ZZZ" (Dual Function) Definitions:		
D0/DIN, D1, D2, D3, D4, D5, D6, D7	Input/Output	• In <i>SelectMAP mode</i>, D0 through D7 are configuration data pins. These pins become user I/Os after configuration, unless the SelectMAP port is retained. • In <i>bit-serial modes</i>, DIN (D0) is the single-data input. This pin becomes a user I/O after configuration.
CS_B	Input	In SelectMAP mode, this is the active-low Chip Select signal. The pin becomes a user I/O after configuration, unless the SelectMAP port is retained.
RDWR_B	Input	In SelectMAP mode, this is the active-low Write Enable signal. The pin becomes a user I/O after configuration, unless the SelectMAP port is retained.
BUSY/DOUT	Output	• In <i>SelectMAP mode</i>, BUSY controls the rate at which configuration data is loaded. The pin becomes a user I/O after configuration, unless the SelectMAP port is retained. • In <i>bit-serial modes</i>, DOUT provides preamble and configuration data to downstream devices in a daisy-chain. The pin becomes a user I/O after configuration.
INIT_B	Bidirectional (open-drain)	When Low, this pin indicates that the configuration memory is being cleared. When held Low, the start of configuration is delayed. During configuration, a Low on this output indicates that a configuration data error has occurred. The pin becomes a user I/O after configuration.

Table 5: FG256/FGG256 — XC2VP2 and XC2VP4

Bank	Pin Description	Pin Number
3	IO_L05P_3	L13
3	IO_L03N_3/VREF_3	L12
3	IO_L03P_3	M13
3	IO_L02N_3	M16
3	IO_L02P_3	N16
3	IO_L01N_3/VRP_3	M15
3	IO_L01P_3/VRN_3	M14
4	IO_L01N_4/BUSY/DOUT ⁽¹⁾	P15
4	IO_L01P_4/INIT_B	P14
4	IO_L02N_4/D0/DIN ⁽¹⁾	R14
4	IO_L02P_4/D1	P13
4	IO_L03N_4/D2	T15
4	IO_L03P_4/D3	T14
4	IO_L06N_4/VRP_4	N12
4	IO_L06P_4/VRN_4	P12
4	IO_L07P_4/VREF_4	N11
4	IO_L09N_4	M11
4	IO_L09P_4/VREF_4	M10
4	IO_L69N_4	N10
4	IO_L69P_4/VREF_4	P10
4	IO_L74N_4/GCLK3S	N9
4	IO_L74P_4/GCLK2P	P9
4	IO_L75N_4/GCLK1S	R9
4	IO_L75P_4/GCLK0P	T9
5	IO_L75N_5/GCLK7S	T8
5	IO_L75P_5/GCLK6P	R8
5	IO_L74N_5/GCLK5S	P8
5	IO_L74P_5/GCLK4P	N8
5	IO_L69N_5/VREF_5	P7
5	IO_L69P_5	N7
5	IO_L09N_5/VREF_5	M7
5	IO_L09P_5	M6
5	IO_L07N_5/VREF_5	N6

FG676/FGG676 Fine-Pitch BGA Package

As shown in [Table 7](#), XC2VP20, XC2VP30, and XC2VP40 Virtex-II Pro devices are available in the FG676/FGG676 fine-pitch BGA package. The pins in these devices are the same, except for the differences shown in the "No Connects" column. Following this table are the [FG676/FGG676 Fine-Pitch BGA Package Specifications \(1.00mm pitch\)](#).

Table 7: FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
0	IO_L01N_0/VRP_0	E5			
0	IO_L01P_0/VRN_0	D5			
0	IO_L02N_0	E6			
0	IO_L02P_0	D6			
0	IO_L03N_0	G7			
0	IO_L03P_0/VREF_0	F7			
0	IO_L05_0/No_Pair	E7			
0	IO_L06N_0	D7			
0	IO_L06P_0	C7			
0	IO_L07N_0	H8			
0	IO_L07P_0	G8			
0	IO_L09N_0	F8			
0	IO_L09P_0/VREF_0	E8			
0	IO_L37N_0	B8			
0	IO_L37P_0	A8			
0	IO_L39N_0	H9			
0	IO_L39P_0	G9			
0	IO_L43N_0	F9			
0	IO_L43P_0	E9			
0	IO_L45N_0	D9			
0	IO_L45P_0/VREF_0	C9			
0	IO_L46N_0	H10			
0	IO_L46P_0	H11			
0	IO_L48N_0	E10			
0	IO_L48P_0	E11			
0	IO_L49N_0	D10			
0	IO_L49P_0	C10			
0	IO_L50_0/No_Pair	G11			
0	IO_L53_0/No_Pair	F11			
0	IO_L54N_0	J12			
0	IO_L54P_0	H12			

Table 7: FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
3	IO_L03P_3	AC25			
3	IO_L02N_3	AC24			
3	IO_L02P_3	AD25			
3	IO_L01N_3/VRP_3	AD26			
3	IO_L01P_3/VRN_3	AE26			
4	IO_L01N_4/BUSY/DOUT ⁽¹⁾	AB22			
4	IO_L01P_4/INIT_B	AC22			
4	IO_L02N_4/D0/DIN ⁽¹⁾	AB21			
4	IO_L02P_4/D1	AC21			
4	IO_L03N_4/D2	Y20			
4	IO_L03P_4/D3	AA20			
4	IO_L05_4/No_Pair	AB20			
4	IO_L06N_4/VRP_4	AC20			
4	IO_L06P_4/VRN_4	AD20			
4	IO_L07N_4	W19			
4	IO_L07P_4/VREF_4	Y19			
4	IO_L09N_4	AA19			
4	IO_L09P_4/VREF_4	AB19			
4	IO_L37N_4	AE19			
4	IO_L37P_4	AF19			
4	IO_L39N_4	W18			
4	IO_L39P_4	Y18			
4	IO_L43N_4	AA18			
4	IO_L43P_4	AB18			
4	IO_L45N_4	AC18			
4	IO_L45P_4/VREF_4	AD18			
4	IO_L46N_4	W17			
4	IO_L46P_4	W16			
4	IO_L48N_4	AB17			
4	IO_L48P_4	AB16			
4	IO_L49N_4	AC17			
4	IO_L49P_4	AD17			
4	IO_L50_4/No_Pair	Y16			
4	IO_L53_4/No_Pair	AA16			

Table 7: FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
N/A	VCCINT	U10			
N/A	VCCINT	U11			
N/A	VCCINT	U16			
N/A	VCCINT	U17			
N/A	VCCINT	U20			
N/A	VCCINT	V9			
N/A	VCCINT	V18			
N/A	VCCINT	Y10			
N/A	VCCINT	Y13			
N/A	VCCINT	Y14			
N/A	VCCINT	Y17			
N/A	VCCAUX	A2			
N/A	VCCAUX	A13			
N/A	VCCAUX	A14			
N/A	VCCAUX	A25			
N/A	VCCAUX	N1			
N/A	VCCAUX	N26			
N/A	VCCAUX	P1			
N/A	VCCAUX	P26			
N/A	VCCAUX	AF2			
N/A	VCCAUX	AF13			
N/A	VCCAUX	AF14			
N/A	VCCAUX	AF25			
N/A	GND	A1			
N/A	GND	A26			
N/A	GND	B2			
N/A	GND	B25			
N/A	GND	C3			
N/A	GND	C24			
N/A	GND	D4			
N/A	GND	D8			
N/A	GND	D19			
N/A	GND	D23			
N/A	GND	F10			
N/A	GND	F17			

Table 8: FF672 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
5	IO_L74P_5/GCLK4P	AB14			
5	IO_L73N_5	AA14			
5	IO_L73P_5	Y14			
5	IO_L69N_5/VREF_5	W14			
5	IO_L69P_5	W15			
5	IO_L68N_5	AD15			
5	IO_L68P_5	AC15			
5	IO_L67N_5	AB15			
5	IO_L67P_5	AA15			
5	IO_L45N_5/VREF_5	AC16	NC	NC	
5	IO_L45P_5	AB16	NC	NC	
5	IO_L44N_5	Y15	NC	NC	
5	IO_L44P_5	Y16	NC	NC	
5	IO_L43N_5	AC17	NC	NC	
5	IO_L43P_5	AB17	NC	NC	
5	IO_L39N_5	AA16	NC	NC	
5	IO_L39P_5	AA17	NC	NC	
5	IO_L38N_5	W16	NC	NC	
5	IO_L38P_5	Y17	NC	NC	
5	IO_L37N_5	AD18	NC	NC	
5	IO_L37P_5	AC18	NC	NC	
5	IO_L09N_5/VREF_5	AA18			
5	IO_L09P_5	Y18			
5	IO_L08N_5	AF19			
5	IO_L08P_5	AE19			
5	IO_L07N_5/VREF_5	AD19			
5	IO_L07P_5	AC19			
5	IO_L06N_5/VRP_5	AB18			
5	IO_L06P_5/VRN_5	AB19			
5	IO_L05_5/No_Pair	Y19			
5	IO_L03N_5/D4	AA19			
5	IO_L03P_5/D5	AA20			
5	IO_L02N_5/D6	AC20			
5	IO_L02P_5/D7	AB20			
5	IO_L01N_5/RDWR_B	AD21			
5	IO_L01P_5/CS_B	AC21			

FF1152 Flip-Chip Fine-Pitch BGA Package

As shown in [Table 10](#), XC2VP20, XC2VP30, XC2VP40, and XC2VP50 Virtex-II Pro devices are available in the FF1152 flip-chip fine-pitch BGA package. Pins in each of these devices are the same, except for the differences shown in the No Connect column. Following this table are the [FF1152 Flip-Chip Fine-Pitch BGA Package Specifications \(1.00mm pitch\)](#).

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
0	IO_L01N_0/VRP_0	E29				
0	IO_L01P_0/VRN_0	E28				
0	IO_L02N_0	H26				
0	IO_L02P_0	G26				
0	IO_L03N_0	H25				
0	IO_L03P_0/VREF_0	G25				
0	IO_L05_0/No_Pair	J25				
0	IO_L06N_0	K24				
0	IO_L06P_0	J24				
0	IO_L07N_0	F26				
0	IO_L07P_0	E26				
0	IO_L08N_0	D30				
0	IO_L08P_0	D29				
0	IO_L09N_0	K23				
0	IO_L09P_0/VREF_0	J23				
0	IO_L19N_0	F24	NC	NC		
0	IO_L19P_0	E24	NC	NC		
0	IO_L20N_0	D28	NC	NC		
0	IO_L20P_0	C28	NC	NC		
0	IO_L21N_0	H24	NC	NC		
0	IO_L21P_0	G24	NC	NC		
0	IO_L25N_0	G23	NC	NC		
0	IO_L25P_0	F23	NC	NC		
0	IO_L26N_0	E27	NC	NC		
0	IO_L26P_0	D27	NC	NC		
0	IO_L27N_0	K22	NC	NC		
0	IO_L27P_0/VREF_0	J22	NC	NC		
0	IO_L37N_0	H22				
0	IO_L37P_0	G22				
0	IO_L38N_0	D26				
0	IO_L38P_0	C26				
0	IO_L39N_0	K21				
0	IO_L39P_0	J21				
0	IO_L43N_0	F22				

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
1	IO_L75N_1/GCLK3P	C17		
1	IO_L75P_1/GCLK2S	B17		
1	IO_L74N_1/GCLK1P	L17		
1	IO_L74P_1/GCLK0S	K17		
1	IO_L73N_1	E17		
1	IO_L73P_1	D17		
1	IO_L69N_1/VREF_1	G17		
1	IO_L69P_1	F17		
1	IO_L68N_1	J17		
1	IO_L68P_1	H17		
1	IO_L67N_1	C16		
1	IO_L67P_1	B16		
1	IO_L66N_1/VREF_1	G16	NC	
1	IO_L66P_1	F16	NC	
1	IO_L57N_1/VREF_1	B15		
1	IO_L57P_1	A15		
1	IO_L56N_1	L16		
1	IO_L56P_1	K16		
1	IO_L55N_1	D16		
1	IO_L55P_1	C15		
1	IO_L54N_1	F15		
1	IO_L54P_1	E15		
1	IO_L53_1/No_Pair	H16		
1	IO_L50_1/No_Pair	G15		
1	IO_L49N_1	B14		
1	IO_L49P_1	A14		
1	IO_L48N_1	D14		
1	IO_L48P_1	C14		
1	IO_L47N_1	L15		
1	IO_L47P_1	K15		
1	IO_L46N_1	F14		
1	IO_L46P_1	E14		
1	IO_L45N_1/VREF_1	H14		
1	IO_L45P_1	G14		
1	IO_L44N_1	L14		
1	IO_L44P_1	K14		
1	IO_L43N_1	C13		

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
6	IO_L87N_6/VREF_6	V33		
6	IO_L88P_6	V30		
6	IO_L88N_6	V31		
6	IO_L89P_6	V24		
6	IO_L89N_6	V25		
6	IO_L90P_6	V28		
6	IO_L90N_6	V29		
7	IO_L90P_7	U32		
7	IO_L90N_7	V32		
7	IO_L89P_7	U28		
7	IO_L89N_7	U29		
7	IO_L88P_7	U30		
7	IO_L88N_7/VREF_7	U31		
7	IO_L87P_7	T33		
7	IO_L87N_7	U33		
7	IO_L86P_7	U26		
7	IO_L86N_7	U27		
7	IO_L85P_7	T31		
7	IO_L85N_7	T32		
7	IO_L60P_7	R33		
7	IO_L60N_7	R34		
7	IO_L59P_7	U24		
7	IO_L59N_7	U25		
7	IO_L58P_7	R29		
7	IO_L58N_7/VREF_7	R30		
7	IO_L57P_7	P33		
7	IO_L57N_7	P34		
7	IO_L56P_7	T28		
7	IO_L56N_7	T29		
7	IO_L55P_7	P32		
7	IO_L55N_7	R32		
7	IO_L54P_7	P29		
7	IO_L54N_7	P30		
7	IO_L53P_7	T24		
7	IO_L53N_7	T25		
7	IO_L52P_7	N32		
7	IO_L52N_7/VREF_7	N33		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
3	IO_L17N_3		AL9		
3	IO_L17P_3		AL10		
3	IO_L16N_3		AM1		
3	IO_L16P_3		AM2		
3	IO_L15N_3/VREF_3		AM3		
3	IO_L15P_3		AN3		
3	IO_L14N_3		AM8		
3	IO_L14P_3		AM9		
3	IO_L13N_3		AM4		
3	IO_L13P_3		AM5		
3	IO_L12N_3		AM6		
3	IO_L12P_3		AM7		
3	IO_L11N_3		AN9		
3	IO_L11P_3		AM10		
3	IO_L10N_3		AN1		
3	IO_L10P_3		AN2		
3	IO_L09N_3/VREF_3		AN5		
3	IO_L09P_3		AN6		
3	IO_L08N_3		AN7		
3	IO_L08P_3		AN8		
3	IO_L07N_3		AP1		
3	IO_L07P_3		AP2		
3	IO_L84N_3		AP4		
3	IO_L84P_3		AP5		
3	IO_L83N_3		AR7		
3	IO_L83P_3		AP8		
3	IO_L82N_3		AP6		
3	IO_L82P_3		AP7		
3	IO_L81N_3/VREF_3		AR2		
3	IO_L81P_3		AR3		
3	IO_L80N_3		AT5		
3	IO_L80P_3		AR6		
3	IO_L79N_3		AR4		
3	IO_L79P_3		AR5		
3	IO_L78N_3		AT1		
3	IO_L78P_3		AT2		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	TXPPAD11		A4		
N/A	GNDA11		C4		
N/A	RXPPAD11		A3		
N/A	RXNPAD11		A2		
N/A	VTRXPAD11		B3		
N/A	AVCCAUXRX11		B2		
N/A	AVCCAUXRX14		BA2		
N/A	VTRXPAD14		BA3		
N/A	RXNPAD14		BB2		
N/A	RXPPAD14		BB3		
N/A	GNDA14		AY4		
N/A	TXPPAD14		BB4		
N/A	TXNPAD14		BB5		
N/A	VTTXPAD14		BA5		
N/A	AVCCAUXTX14		BA4		
N/A	AVCCAUXRX15		BA6		
N/A	VTRXPAD15		BA7		
N/A	RXNPAD15		BB6		
N/A	RXPPAD15		BB7		
N/A	GNDA15		AY8		
N/A	TXPPAD15		BB8		
N/A	TXNPAD15		BB9		
N/A	VTTXPAD15		BA9		
N/A	AVCCAUXTX15		BA8		
N/A	AVCCAUXRX16		BA10		
N/A	VTRXPAD16		BA11		
N/A	RXNPAD16		BB10		
N/A	RXPPAD16		BB11		
N/A	GNDA16		AY12		
N/A	TXPPAD16		BB12		
N/A	TXNPAD16		BB13		
N/A	VTTXPAD16		BA13		
N/A	AVCCAUXTX16		BA12		
N/A	AVCCAUXRX17		BA14		
N/A	VTRXPAD17		BA15		
N/A	RXNPAD17		BB14		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
4	IO_L39N_4	AM16	
4	IO_L39P_4	AL16	
4	IO_L43N_4	AR17	
4	IO_L43P_4	AR16	
4	IO_L44N_4	AV16	
4	IO_L44P_4	AU16	
4	IO_L45N_4	AP16	
4	IO_L45P_4/VREF_4	AN16	
4	IO_L10N_4	AW17	NC
4	IO_L10P_4	AW16	NC
4	IO_L11N_4	BB16	NC
4	IO_L11P_4	BA16	NC
4	IO_L12N_4	AL18	NC
4	IO_L12P_4	AL17	NC
4	IO_L16N_4	AU17	NC
4	IO_L16P_4	AT17	NC
4	IO_L18N_4	BA17	NC
4	IO_L18P_4/VREF_4	AY17	NC
4	IO_L46N_4	AT19	
4	IO_L46P_4	AT18	
4	IO_L47N_4	AN17	
4	IO_L47P_4	AM17	
4	IO_L48N_4	AV18	
4	IO_L48P_4	AU18	
4	IO_L49N_4	AY19	
4	IO_L49P_4	AY18	
4	IO_L50_4/No_Pair	AM19	
4	IO_L53_4/No_Pair	AM18	
4	IO_L54N_4	BB18	
4	IO_L54P_4	BA18	
4	IO_L55N_4	AR20	
4	IO_L55P_4	AR19	
4	IO_L56N_4	AP18	
4	IO_L56P_4	AN18	
4	IO_L57N_4	AV19	
4	IO_L57P_4/VREF_4	AU19	
4	IO_L58N_4	AW20	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
7	IO_L45N_7	T36	
7	IO_L44P_7	W32	
7	IO_L44N_7	W33	
7	IO_L43P_7	R41	
7	IO_L43N_7	R42	
7	IO_L42P_7	P40	
7	IO_L42N_7	R40	
7	IO_L41P_7	V36	
7	IO_L41N_7	V37	
7	IO_L40P_7	R38	
7	IO_L40N_7/VREF_7	R39	
7	IO_L39P_7	P38	
7	IO_L39N_7	R37	
7	IO_L38P_7	V34	
7	IO_L38N_7	V35	
7	IO_L37P_7	P41	
7	IO_L37N_7	P42	
7	IO_L36P_7	P36	
7	IO_L36N_7	P37	
7	IO_L35P_7	V32	
7	IO_L35N_7	V33	
7	IO_L34P_7	M41	
7	IO_L34N_7/VREF_7	N41	
7	IO_L33P_7	N39	
7	IO_L33N_7	N40	
7	IO_L32P_7	U35	
7	IO_L32N_7	U36	
7	IO_L31P_7	N36	
7	IO_L31N_7	N37	
7	IO_L30P_7	M39	
7	IO_L30N_7	M40	
7	IO_L29P_7	U32	
7	IO_L29N_7	U33	
7	IO_L28P_7	M37	
7	IO_L28N_7/VREF_7	M38	
7	IO_L27P_7	L37	
7	IO_L27N_7	M36	